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(54) MANUFACTURE OF ELECTRIC LAMINATED BOARD

(57) Abstract:

PURPOSE: To enable a lamination having no recess and protrusion in its surface to be carried out by integrating a prepreg in overlaying on one surface of a metallic plate provided with penetrating hole, and lamination-forming the composition of the metallic plate and the prepreg after a specific resin is filled into the penetrating holes, and performing then a punching work at the part of the resin.

CONSTITUTION: Since the resin 4 containing a filling agent is filled previously into penetrating holes in a state of prepreg 3a overlaid on one surface of a metallic plate 2, recess and protrusion can be prevented from being produced, which tends to occur in the case wherein resin is flown into the penetrating holes 1 from the prepgs 3a, 3b during the period of molding, furthermore, by making the difference of a heat expansion between the metallic plate 2 and the resin 4 containing a filling agent to be 20ppm°C or below, the occurrence of recess and protrusion is prevented at the part of the metallic plate 2 and the resin 4 through the difference

of a heat expansion. After the metallic plate 2 and a circuit plate 12 are laminated alternatively, and a metallic foil 13 is laminated on the surface, through holes 5 are worked by punching through drilling work and punching work. Through holes 5 are formed in the part of the resin 4 filled into the penetrating holes 1 in a smaller diameter than that of the penetrating holes 1.

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